

Description

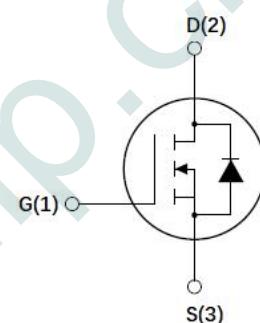
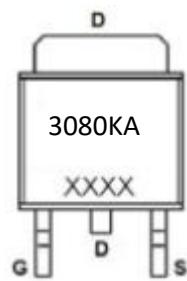
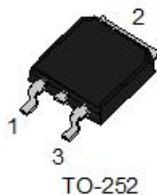
Features

- 30V,80A
- $R_{DS(ON)}=3.7m\Omega$ (Typ.) @ $V_{GS}=10V$
- $R_{DS(ON)}=5.3m\Omega$ (Typ.) @ $V_{GS}=4.5V$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge

Application

- Load Switch
- PWM Application

Package



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	80	A
		$T_c = 100^\circ C$	56	A
I_{DM}	Pulsed Drain Current ^{note1}		224	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		225	mJ
P_D	Power Dissipation	$T_c = 25^\circ C$	76	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.89	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ C$

Electrical Characteristics (T_C=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.1	1.5	1.9	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =20A	-	3.7	4.5	mΩ
		V _{GS} =4.5V, I _D =20A	-	5.3	6.8	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A	-	5.798	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1.0MHz	-	1800		pF
C _{oss}	Output Capacitance		-	269	-	pF
C _{rss}	Reverse Transfer Capacitance		-	247	-	pF
Q _{g10V}	Total Gate Charge		-	38.8	-	nC
Q _{g4.5V}	Total Gate Charge	V _{DS} =15V, I _D =20A, V _{GS} =10V	-	18.9	-	nC
Q _{gs}	Gate-Source Charge		-	6.9	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	8.7	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =15V, I _D =20A, R _{GEN} =3Ω, RL=0.75Ω, V _{GS} =10V	-	8.4	-	ns
t _r	Turn-on Rise Time		-	64.8	-	ns
t _{d(off)}	Turn-off Delay Time		-	32.3	-	ns
t _f	Turn-off Fall Time		-	51.2	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _s	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	224	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _s =30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=100A/μs	-	49.66		ns
Qrr	Body Diode Reverse Recovery Charge		-	34.25	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25°C, V_{DD}=20V, V_G=10V, R_G=25Ω, L=0.5mH

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

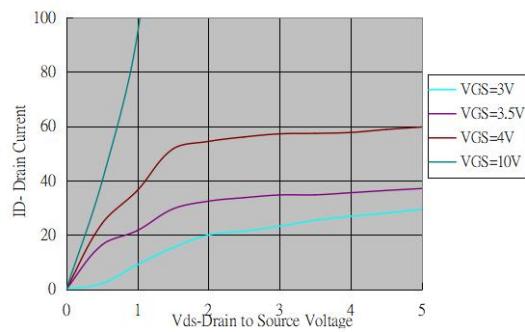


Figure 1: Output Characteristics I_D (A)

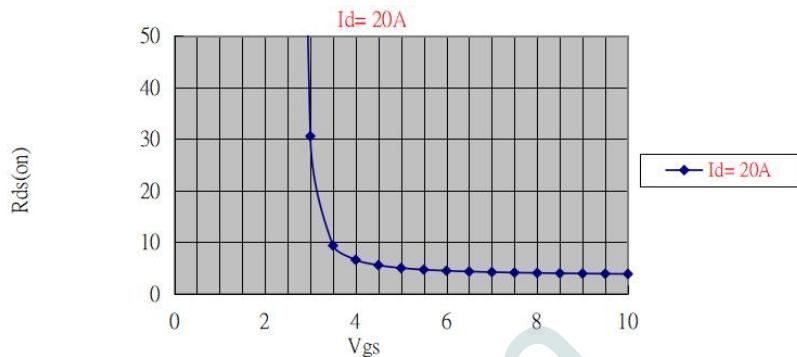


Figure 2: Typical Transfer Characteristics I_D (A)

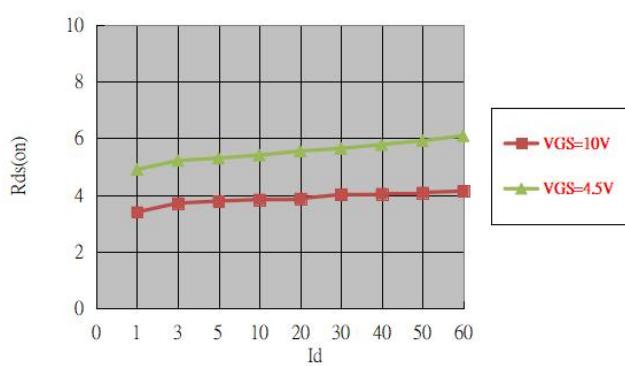


Figure 3: On-resistance vs. Drain Current $R_{DS(ON)}$ (mΩ)

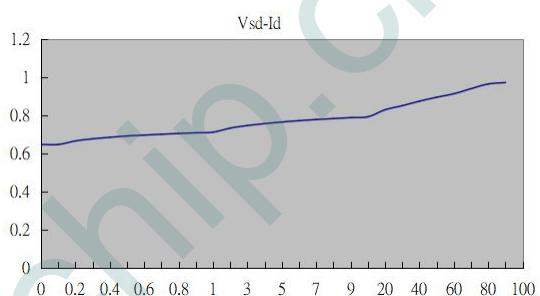


Figure 4: Body Diode Characteristics I_S (A)

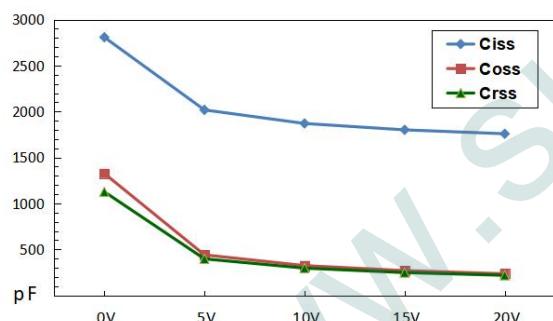


Figure 5: Capacitance Characteristics C (pF)

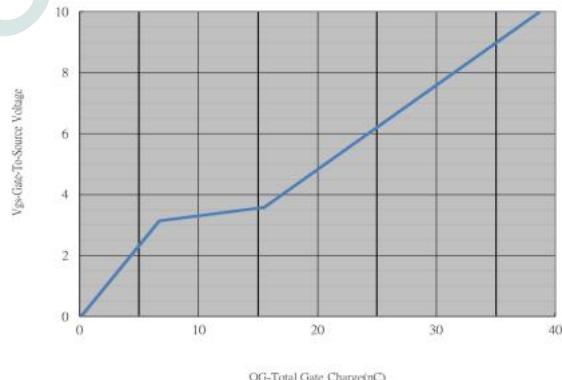


Figure 6: Gate-Charge Characteristics Q_g (nC)

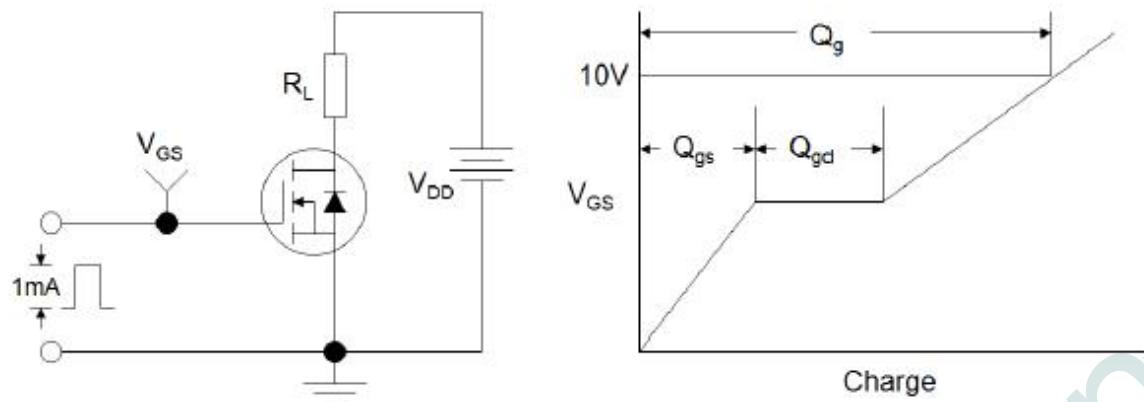


Figure1:Gate Charge Test Circuit & Waveform

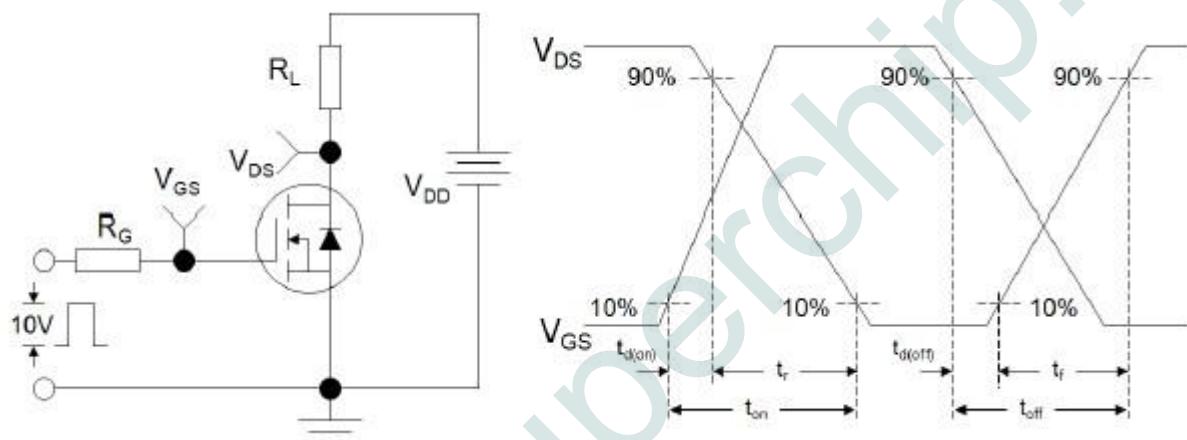


Figure 2: Resistive Switching Test Circuit & Waveforms

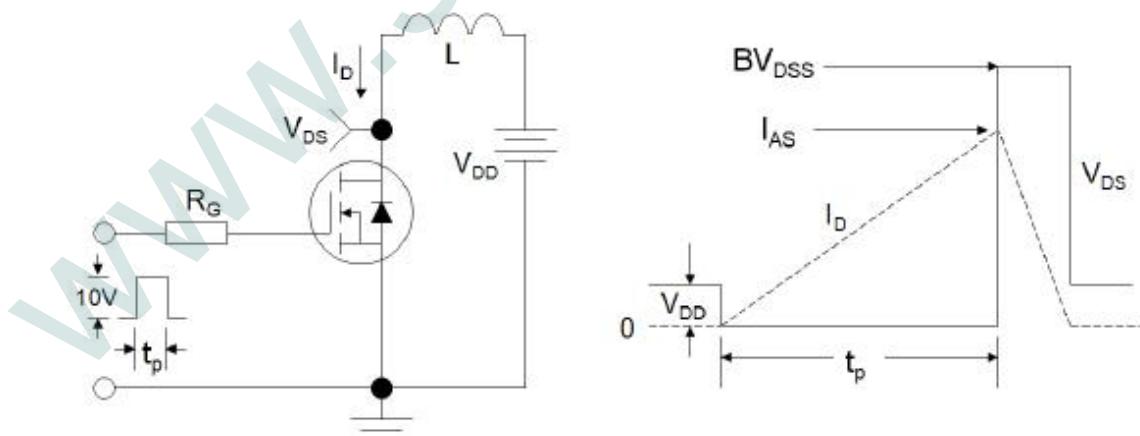


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

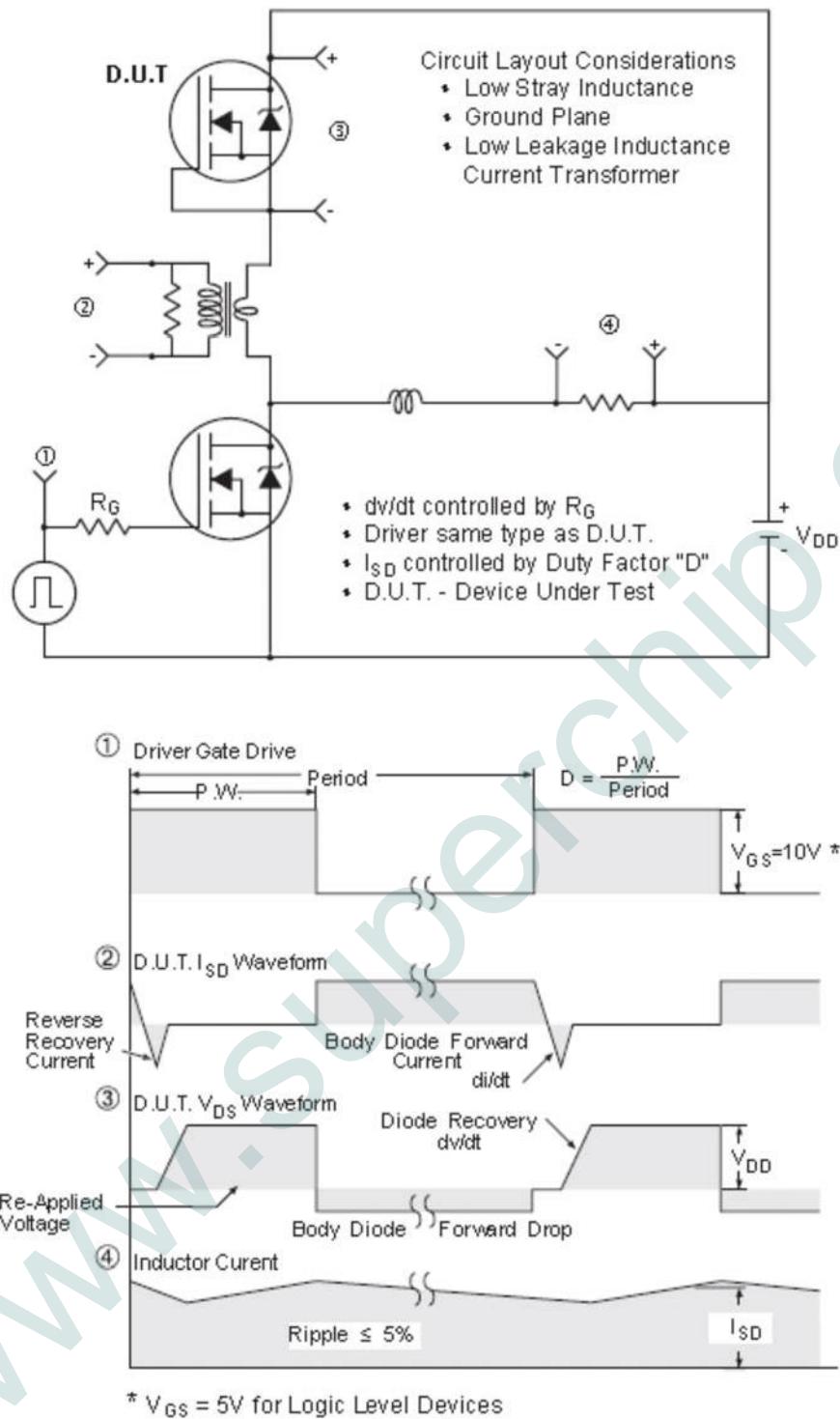
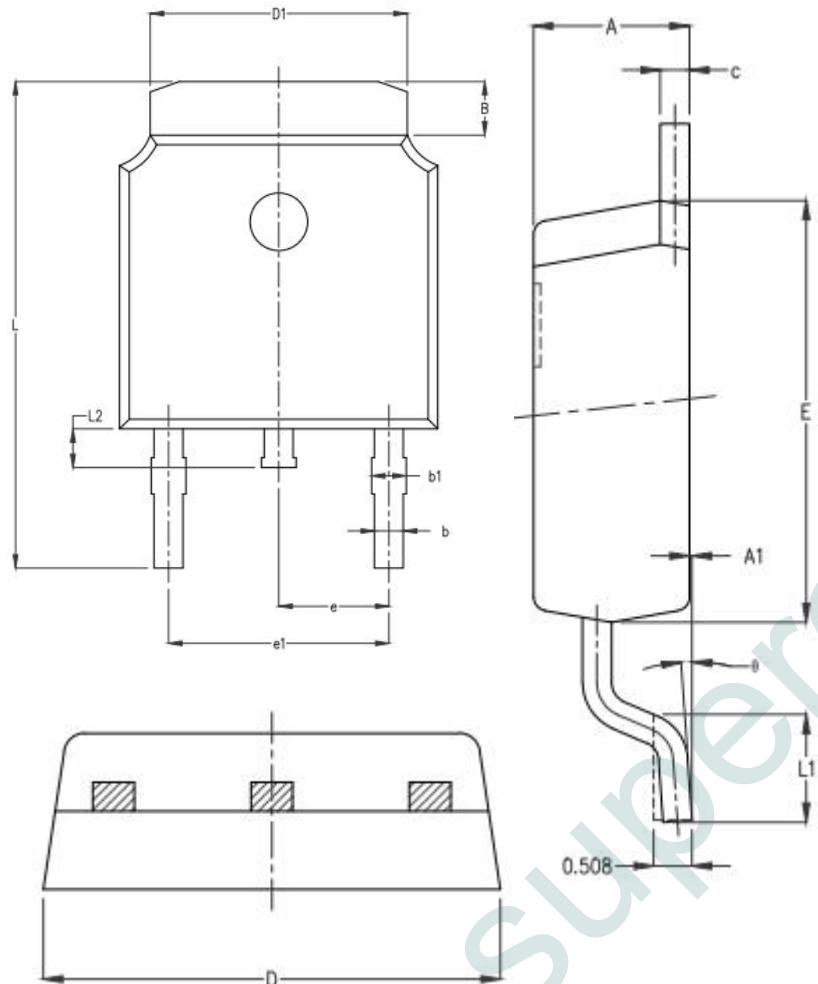


Figure 4:Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)

TO-252 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.15	2.25	2.35
A1	0.00	0.06	0.12
B	0.96	1.11	1.26
b	0.59	0.69	0.79
b1	0.69	0.81	0.93
c	0.34	0.42	0.50
D	6.45	6.60	6.75
D1	5.23	5.33	5.43
E	5.95	6.10	6.25
e	2.286TYP.		
e1	4.47	4.57	4.67
L	9.90	10.10	10.30
L1	1.40	1.55	1.70
L2	0.60	0.80	1.00
θ	0°	4°	8°